

TOSHIBA RECTIFIER SILICON DIFFUSED TYPE

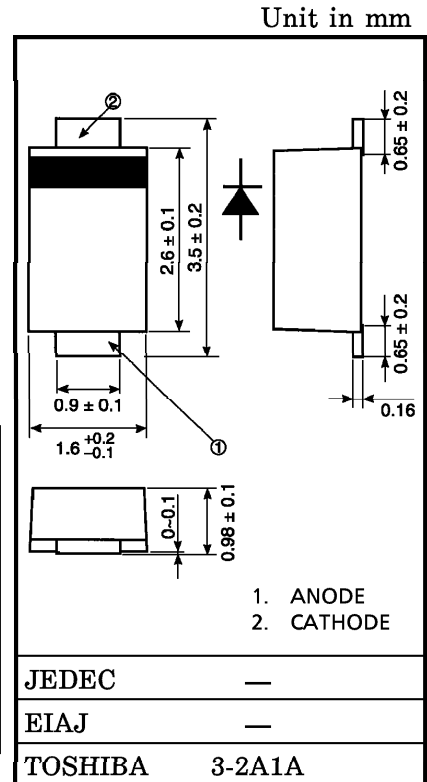
# CRG01, CRG02

GENERAL PURPOSE RECTIFIER APPLICATIONS

- Average Forward Current :  $I_F (AV) = 0.7 A$
- Repetitive Peak Reverse Voltage :  $V_{RRM} = 100, 400 V$
- Small Package : “S-FLAT” (Toshiba designation)

MAXIMUM RATINGS

CHARACTERISTIC		SYMBOL	RATING	UNIT
Repetitive Peak Reverse Voltage	CRG01	$V_{RRM}$	100	V
	CRG02		400	
Average Forward Current		$I_F (AV)$	0.7	A
Peak One Cycle Surge Forward Current (Non-Repetitive)		$I_{FSM}$	15 (50 Hz)	A
			16.5 (60 Hz)	
Junction Temperature		$T_j$	-40~150	°C
Storage Temperature Range		$T_{stg}$	-40~150	°C



Weight : 0.013 g

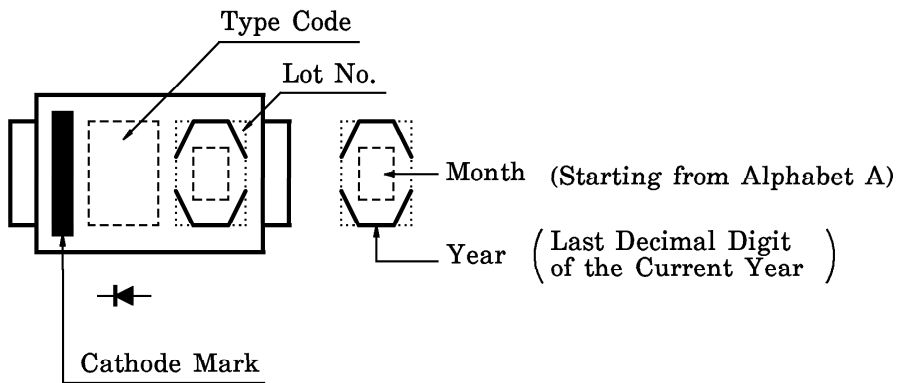
ELECTRICAL CHARACTERISTICS (Ta = 25°C)

CHARACTERISTIC	SYMBOL	TEST CONDITION	TYP.	MAX.	UNIT
Peak Forward Voltage	$V_{FM} (1)$	$I_{FM} = 0.1 A$	0.88	—	V
	$V_{FM} (2)$	$I_{FM} = 0.7 A$	—	1.1	
	$V_{FM} (3)$	$I_{FM} = 1.0 A$	1.10	—	
Repetitive Peak Reverse Current	$I_{RRM}$	$V_{RRM} = \text{Rated}$	—	10	$\mu A$
Thermal Resistance	$r_{th} (j-a)$ (DC)	On ceramic substrate	—	65	°C / W
		On glass-epoxy substrate	—	130	

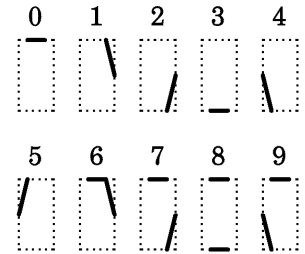
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**MARKING**



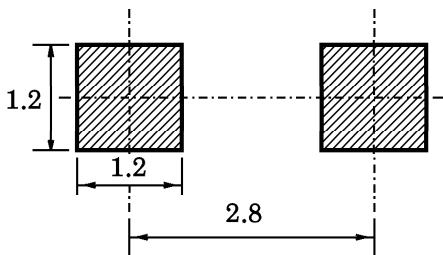
FOLLOWING INDICATES THE DATE OF MANUFACTURE

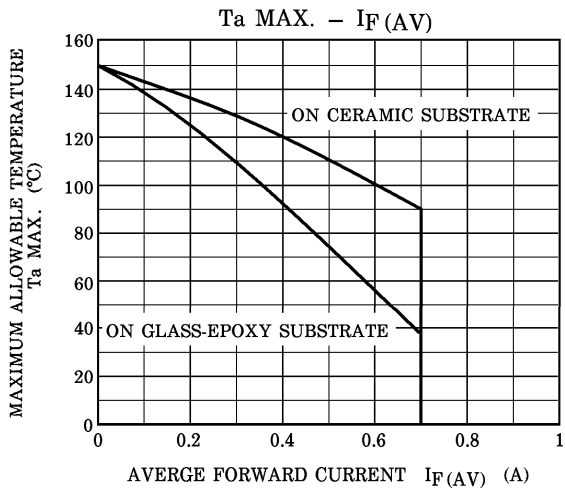
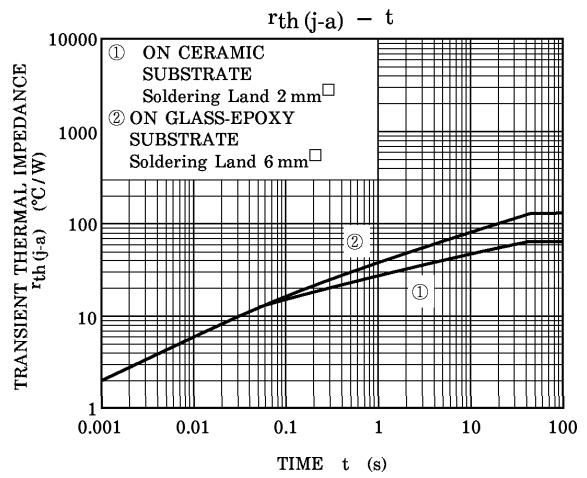
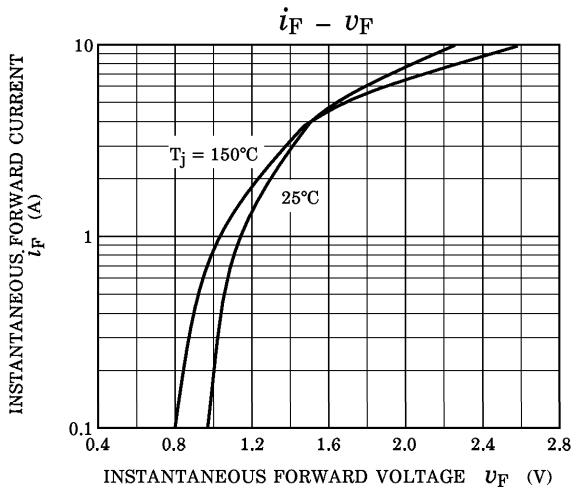


TYPE	CODE
CRG01	G1
CRG02	G2

**STANDARD SOLDERING PAD**

Unit : mm





	ON CERAMIC SUBSTRATE	ON GLASS-EPOXY SUBSTRATE
Soldering Land	2 mm <sup>2</sup>	6 mm <sup>2</sup>
Substrate Size	50 mm <sup>2</sup>	50 mm <sup>2</sup>
Substrate Thickness	0.64 t	1.6 t

